

**Pin Definition:**

1. Gate
2. Drain
3. Source

**PRODUCT SUMMARY**

V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (mΩ)	I <sub>D</sub> (A)
75	8 @ V <sub>GS</sub> =10V	80

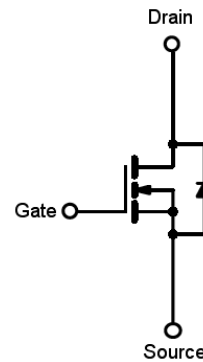
**Features**

- Advanced Trench Technology
- Low R<sub>DS(ON)</sub> 8mΩ (Max.)
- Low gate charge typical @ 91.5nC (Typ.)
- Low Crss typical @ 203pF (Typ.)

**Ordering Information**

Part No.	Package	Packing
TSM80N08CZ C0	TO-220	50pcs / Tube

**Block Diagram**



N-Channel MOSFET

**Absolute Maximum Rating** (Ta = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	75	V	
Gate-Source Voltage	V <sub>GS</sub>	±25	V	
Continuous Drain Current	I <sub>D</sub>	T <sub>C</sub> =25°C	80	A
		T <sub>C</sub> =70°C	60	
		T <sub>A</sub> =25°C	12	
		T <sub>A</sub> =70°C	9	
Drain Current-Pulsed Note 1	I <sub>DM</sub>	320	A	
Avalanche Current, L=0.3mH	I <sub>AS</sub> , I <sub>AR</sub>	58	A	
Avalanche Energy, L=0.3mH	E <sub>AS</sub> , E <sub>AR</sub>	400	mJ	
Maximum Power Dissipation	P <sub>D</sub>	T <sub>C</sub> =25°C	113.6	W
		T <sub>C</sub> =70°C	72.7	
		T <sub>A</sub> =25°C	2	
		T <sub>A</sub> =70°C	1.3	
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C	
Operating Junction Temperature Range	T <sub>J</sub>	-55 to +150	°C	

\* Limited by maximum junction temperature

**Thermal Performance**

Parameter	Symbol	Limit	Unit
Thermal Resistance - Junction to Case	Rθ <sub>JC</sub>	1.1	°C/W
Thermal Resistance - Junction to Ambient	Rθ <sub>JA</sub>	62.5	°C/W

Notes: Surface mounted on FR4 board t ≤ 10sec

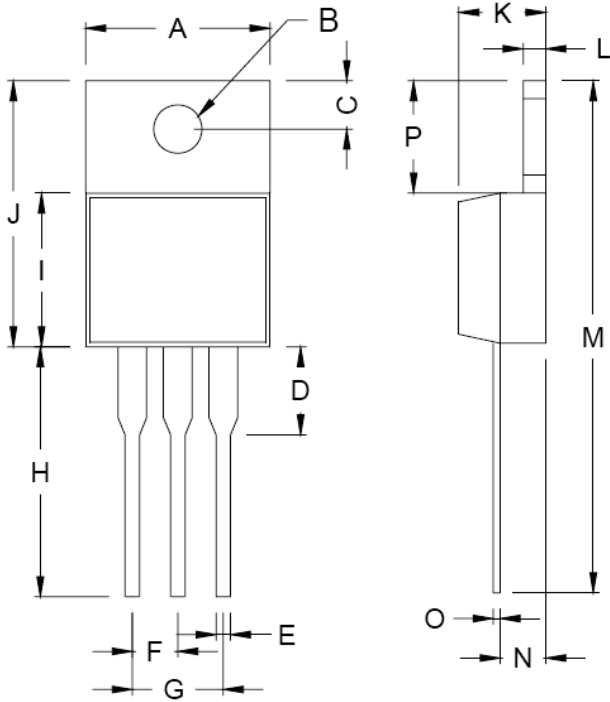
**Electrical Specifications** (Ta = 25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	BV <sub>DSS</sub>	75	--	--	V
Drain-Source On-State Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 40A	R <sub>DS(ON)</sub>	--	7	8	mΩ
Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	V <sub>GS(TH)</sub>	2	3	4	V
Zero Gate Voltage Drain Current	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V	I <sub>DSS</sub>	--	--	1	μA
Gate Body Leakage	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	I <sub>GSS</sub>	--	--	±100	nA
<b>Dynamic</b>						
Total Gate Charge	V <sub>DS</sub> = 30V, I <sub>D</sub> = 40A, V <sub>GS</sub> = 10V	Q <sub>g</sub>	--	91.5	--	nC
Gate-Source Charge		Q <sub>gs</sub>	--	34	--	
Gate-Drain Charge		Q <sub>gd</sub>	--	19.9	--	
Input Capacitance	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V, f = 1.0MHz	C <sub>iss</sub>	--	3905	--	pF
Output Capacitance		C <sub>oss</sub>	--	371	--	
Reverse Transfer Capacitance		C <sub>rss</sub>	--	203	--	
<b>Switching</b>						
Turn-On Delay Time	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 30V, R <sub>G</sub> = 3.3Ω	t <sub>d(on)</sub>	--	21.5	--	nS
Turn-On Rise Time		t <sub>r</sub>	--	11	--	
Turn-Off Delay Time		t <sub>d(off)</sub>	--	73	--	
Turn-Off Fall Time		t <sub>f</sub>	--	66	--	
<b>Drain-Source Diode Characteristics and Maximum Rating</b>						
Drain-Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =20A	V <sub>SD</sub>	-	0.8	1.3	V
Reverse Recovery Time	I <sub>S</sub> = 40A, T <sub>J</sub> =25°C dI/dt = 100A/μs	t <sub>fr</sub>		36		nS
Reverse Recovery Charge		Q <sub>fr</sub>		45		nC

**Notes:**

- Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
- R<sub>θJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>θJC</sub> is guaranteed by design while R<sub>θCA</sub> is determined by the user's board design. R<sub>θJA</sub> shown below for single device operation on FR-4 in still air

**TO-220 Mechanical Drawing**



TO-220 DIMENSION				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.000	10.500	0.394	0.413
B	3.740	3.910	0.147	0.154
C	2.440	2.940	0.096	0.116
D	-	6.350	-	0.250
E	0.381	1.106	0.015	0.040
F	2.345	2.715	0.092	0.058
G	4.690	5.430	0.092	0.107
H	12.700	14.732	0.500	0.581
J	14.224	16.510	0.560	0.650
K	3.556	4.826	0.140	0.190
L	0.508	1.397	0.020	0.055
M	27.700	29.620	1.060	1.230
N	2.032	2.921	0.080	0.115
O	0.255	0.610	0.010	0.024
P	5.842	6.858	0.230	0.270

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